



RE900-06

- EPOXY fibre-glass FR4 1.50 mm
- Double-sided 35 µm Cu
- Plated through holes (PTH)
- Surface chem. Ni/Au with solder stop mask
- Adaption circuit board for TSOP II 20, 24, 26, 28, 32 (1.27 mm)
- Hole diameter 1.00 mm
- Gerber data for manufacture of the soldering paste imprint will be provided free of charge on request
- Size 26.50 x 30.94 mm

Module-No.	Type	Pitch	Pin	Size (mm)
RE900-06	TSOP II	1.270 mm	20, 24, 26, 28, 32	11.50 x 21.30